

C0603X229CATACAUTO7411

SMD Auto X8G HT150C Flex, Ceramic, 2.2 pF, +/-0.25 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 0603, 0.4 mm



General Information		
Series	SMD Auto X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade	
Features	High Temperature, Ultra-Stable, Automotive Grade	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
Qualifications	AEC-Q200	
AEC-Q200	Yes	
Typical Component Weight	4.6 mg	
Shelf Life	78 Weeks	
MSL	1	

2.2 pF

1 MHz 1.0Vrms

100 GOhms

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

W 0.	.8mm +/-0.15mm
Т 0.	.8mm +/-0.15mm
S 0.	.4mm MIN
В 0.	.45mm +/-0.15mm

W	0.8mm +/-0.15mm	Tolerance	+/-0.25 pF
Т	0.8mm +/-0.15mm	Voltage DC	250 VDC
S	0.4mm MIN	Dielectric Withstanding Voltage	625 VDC
В	0.45mm +/-0.15mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 330mm, Paper Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity 15000	Dissipation Factor	0.1% 1 MHz 1.0Vrms	
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Specifications Capacitance

Measurement Condition

Insulation Resistance

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